

MC74HC245A

Octal 3-State Noninverting Bus Transceiver High-Performance Silicon-Gate CMOS

The MC74HC245A is identical in pinout to the LS245. The device inputs are compatible with standard CMOS outputs; with pull-up resistors, they are compatible with LSTTL outputs.

The HC245A is a 3-state noninverting transceiver that is used for 2-way asynchronous communication between data buses. The device has an active-low Output Enable pin, which is used to place the I/O ports into high-impedance states. The Direction control determines whether data flows from A to B or from B to A.

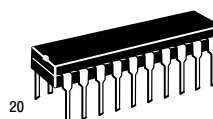
- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Moisture Sensitivity: MSL1 for All Packages
- Chip Complexity: 308 FETs or 77 Equivalent Gates



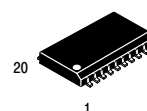
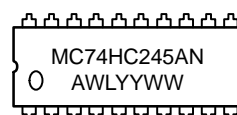
ON Semiconductor™

<http://onsemi.com>

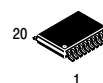
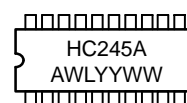
MARKING DIAGRAMS



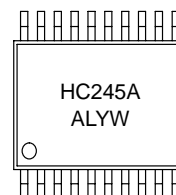
1
PDIP-20
N SUFFIX
CASE 783



1
SO-20
DW SUFFIX
CASE 751D



1
TSSOP-20
DT SUFFIX
CASE 948E



A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|----------|------------------|
| MC74HC245AN | PDIP-20 | 18 Units/Rail |
| MC74HC245ADW | SOIC-20 | 38 Units/Rail |
| MC74HC245ADWR2 | SOIC-20 | 1000 Tape & Reel |
| MC74HC245ADT | TSSOP-20 | 75 Units/Rail |
| MC74HC245ADTR2 | TSSOP-20 | 2500 Tape & Reel |

MC74HC245A

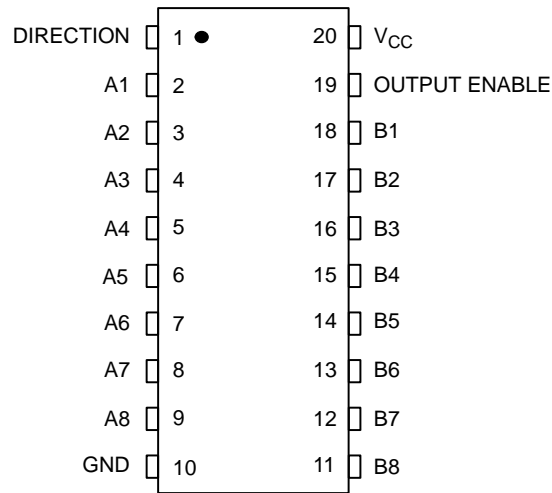


Figure 1. Pin Assignment

FUNCTION TABLE

| Control Inputs | | Operation |
|----------------|-----------|---------------------------------------|
| Output Enable | Direction | |
| L | L | Data Transmitted from Bus B to Bus A |
| L | H | Data Transmitted from Bus A to Bus B |
| H | X | Buses Isolated (High-Impedance State) |

X = don't care

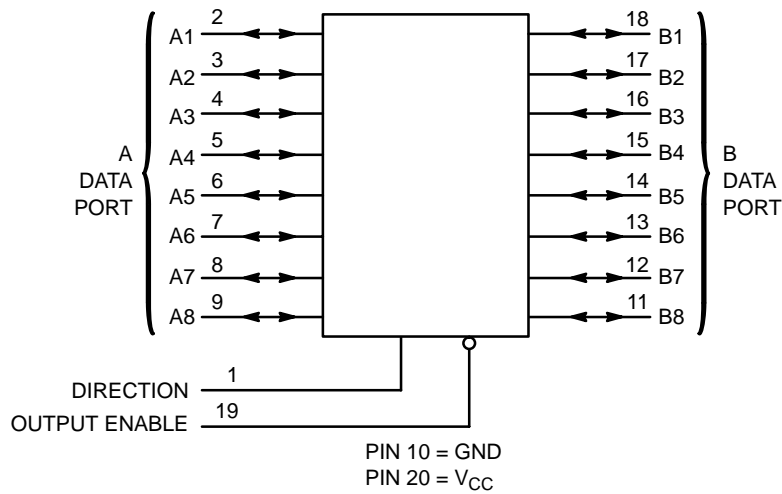


Figure 2. Logic Diagram

MC74HC245A

MAXIMUM RATINGS (Note 1.)

| Symbol | Parameter | Value | Unit |
|-----------------------|--|------------------------------|------|
| V _{CC} | DC Supply Voltage | -0.5 to +7.0 | V |
| V _{IN} | DC Input Voltage | -0.5 to V _{CC} +0.5 | V |
| V _{OUT} | DC Output Voltage (Note 2.) | -0.5 to V _{CC} +0.5 | V |
| I _{IK} | DC Input Diode Current | ±20 | mA |
| I _{OK} | DC Output Diode Current | ±35 | mA |
| I _{OUT} | DC Output Sink Current | ±35 | mA |
| I _{CC} | DC Supply Current per Supply Pin | ±75 | mA |
| I _{GND} | DC Ground Current per Ground Pin | ±75 | mA |
| T _{STG} | Storage Temperature Range | -65 to +150 | °C |
| T _L | Lead Temperature, 1 mm from Case for 10 Seconds | 260 | °C |
| T _J | Junction Temperature Under Bias | +150 | °C |
| θ _{JA} | Thermal Resistance PDIP SOIC TSSOP | 67 96 128 | °C/W |
| P _D | Power Dissipation in Still Air at 85°C PDIP SOIC TSSOP | 750 500 450 | mW |
| MSL | Moisture Sensitivity | Level 1 | |
| F _R | Flammability Rating Oxygen Index: 30% to 35% | UL 94 V-0 @ 0.125 in | |
| V _{ESD} | ESD Withstand Voltage Human Body Model (Note 3.) Machine Model (Note 4.) Charged Device Model (Note 5.) | >2000 >200 >1000 | V |
| I _{LATCH-UP} | Latch-Up Performance Above V _{CC} and Below GND at 85°C (Note 6.) | ±300 | mA |

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 20 ounce copper trace with no air flow.
2. I_O absolute maximum rating must be observed.
3. Tested to EIA/JESD22-A114-A.
4. Tested to EIA/JESD22-A115-A.
5. Tested to JESD22-C101-A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|------------------------------------|--|-------------------------|-----------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V |
| V _{in} , V _{out} | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | V _{CC} | V |
| T _A | Operating Temperature, All Package Types | -55 | +125 | °C |
| t _r , t _f | Input Rise and Fall Time (Figure 3) | | | ns |
| | | V _{CC} = 2.0 V | 0 | 1000 |
| | | V _{CC} = 4.5 V | 0 | 500 |
| | | V _{CC} = 6.0 V | 0 | 400 |

MC74HC245A

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Test Conditions | V _{CC} V | Guaranteed Limit | | | Unit |
|-----------------|--|---|--|------------------|--------|---------|------|
| | | | | -55 to 25°C | ≤ 85°C | ≤ 125°C | |
| V _{IH} | Minimum High-Level Input Voltage | V _{out} = V _{CC} - 0.1 V I _{out} ≤ 20 μA | 2.0 | 1.5 | 1.5 | 1.5 | V |
| | | | 3.0 | 2.1 | 2.1 | 2.1 | |
| | | | 4.5 | 3.15 | 3.15 | 3.15 | |
| | | | 6.0 | 4.2 | 4.2 | 4.2 | |
| V _{IL} | Maximum Low-Level Input Voltage | V _{out} = 0.1 V I _{out} ≤ 20 μA | 2.0 | 0.5 | 0.5 | 0.5 | V |
| | | | 3.0 | 0.9 | 0.9 | 0.9 | |
| | | | 4.5 | 1.35 | 1.35 | 1.35 | |
| | | | 6.0 | 1.8 | 1.8 | 1.8 | |
| V _{OH} | Minimum High-Level Output Voltage | V _{in} = V _{IH} I _{out} ≤ 20 μA | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | | | 4.5 | 4.4 | 4.4 | 4.4 | |
| | | | 6.0 | 5.9 | 5.9 | 5.9 | |
| | | | V _{in} = V _{IH} I _{out} ≤ 2.4 mA | 3.0 | 2.48 | 2.34 | |
| | I _{out} ≤ 6.0 mA | 4.5 | 3.98 | 3.84 | 3.7 | | |
| | I _{out} ≤ 7.8 mA | 6.0 | 5.48 | 5.34 | 5.2 | | |
| V _{OL} | Maximum Low-Level Output Voltage | V _{in} = V _{IL} I _{out} ≤ 20 μA | 2.0 | 0.1 | 0.1 | 0.1 | V |
| | | | 4.5 | 0.1 | 0.1 | 0.1 | |
| | | | 6.0 | 0.1 | 0.1 | 0.1 | |
| | | | V _{in} = V _{IL} I _{out} ≤ 2.4 mA | 3.0 | 0.26 | 0.33 | |
| | I _{out} ≤ 6.0 mA | 4.5 | 0.26 | 0.33 | 0.4 | | |
| | I _{out} ≤ 7.8 mA | 6.0 | 0.26 | 0.33 | 0.4 | | |
| I _{in} | Maximum Input Leakage Current | V _{in} = V _{CC} or GND | 6.0 | ±0.1 | ±1.0 | ±1.0 | μA |
| I _{oz} | Maximum Three-State Leakage Current | Output in High-Impedance State V _{in} = V _{IL} or V _{IH} V _{out} = V _{CC} or GND | 6.0 | ±0.5 | ±5.0 | ±10 | μA |
| I _{CC} | Maximum Quiescent Supply Current (per Package) | V _{in} = V _{CC} or GND I _{out} = 0 μA | 6.0 | 4.0 | 40 | 160 | μA |

7. Information on typical parametric values and high frequency or heavy load considerations can be found in the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6 ns)

| Symbol | Parameter | V _{CC} V | Guaranteed Limit | | | Unit |
|--|---|----------------------|------------------|--------|---------|------|
| | | | -55 to 25°C | ≤ 85°C | ≤ 125°C | |
| t _{PLH} , t _{PHL} | Maximum Propagation Delay, A to B, B to A (Figures 1 and 3) | 2.0 | 75 | 95 | 110 | ns |
| | | 3.0 | 55 | 70 | 80 | |
| | | 4.5 | 15 | 19 | 22 | |
| | | 6.0 | 13 | 16 | 19 | |
| t _{PLZ} , t _{PHZ} | Maximum Propagation Delay, Direction or Output Enable to A or B (Figures 2 and 4) | 2.0 | 110 | 140 | 165 | ns |
| | | 3.0 | 90 | 110 | 130 | |
| | | 4.5 | 22 | 28 | 33 | |
| | | 6.0 | 19 | 24 | 28 | |
| t _{PZL} , t _{PZH} | Maximum Propagation Delay, Output Enable to A or B (Figures 2 and 4) | 2.0 | 110 | 140 | 165 | ns |
| | | 3.0 | 90 | 110 | 130 | |
| | | 4.5 | 22 | 28 | 33 | |
| | | 6.0 | 19 | 24 | 28 | |
| t _{TLH} , t _{THL} | Maximum Output Transition Time, Any Output (Figures 1 and 3) | 2.0 | 60 | 75 | 90 | ns |
| | | 3.0 | 23 | 27 | 32 | |
| | | 4.5 | 12 | 15 | 18 | |
| | | 6.0 | 10 | 13 | 15 | |
| C _{in} | Maximum Input Capacitance (Pin 1 or Pin 19) | — | 10 | 10 | 10 | pF |
| C _{out} | Maximum Three-State I/O Capacitance (I/O in High-Impedance State) | — | 15 | 15 | 15 | pF |

8. For propagation delays with loads other than 50 pF, and information on typical parametric values, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

| C _{PD} | Power Dissipation Capacitance (Per Transceiver Channel) (Note 9.) | Typical @ 25°C, V _{CC} = 5.0 V | pF |
|-----------------|---|---|----|
| | | 40 | |

9. Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

MC74HC245A

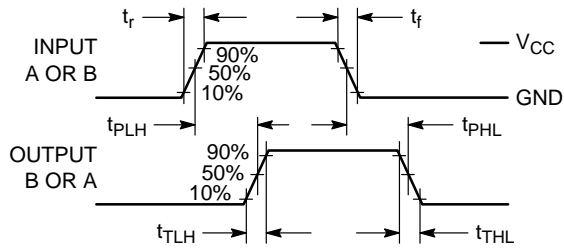


Figure 3. Switching Waveform

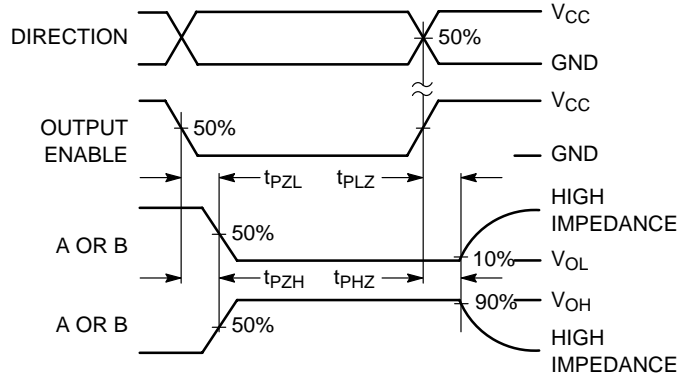
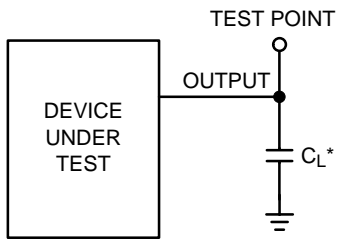
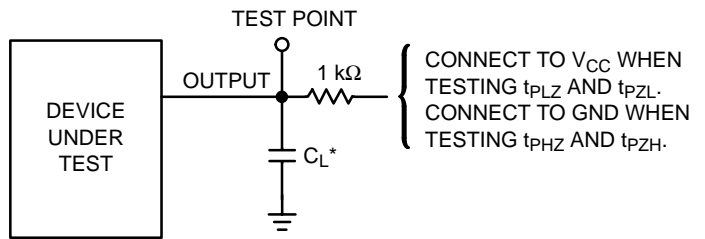


Figure 4. Switching Waveform



*Includes all probe and jig capacitance

Figure 5. Test Circuit



*Includes all probe and jig capacitance

Figure 6. Test Circuit

MC74HC245A

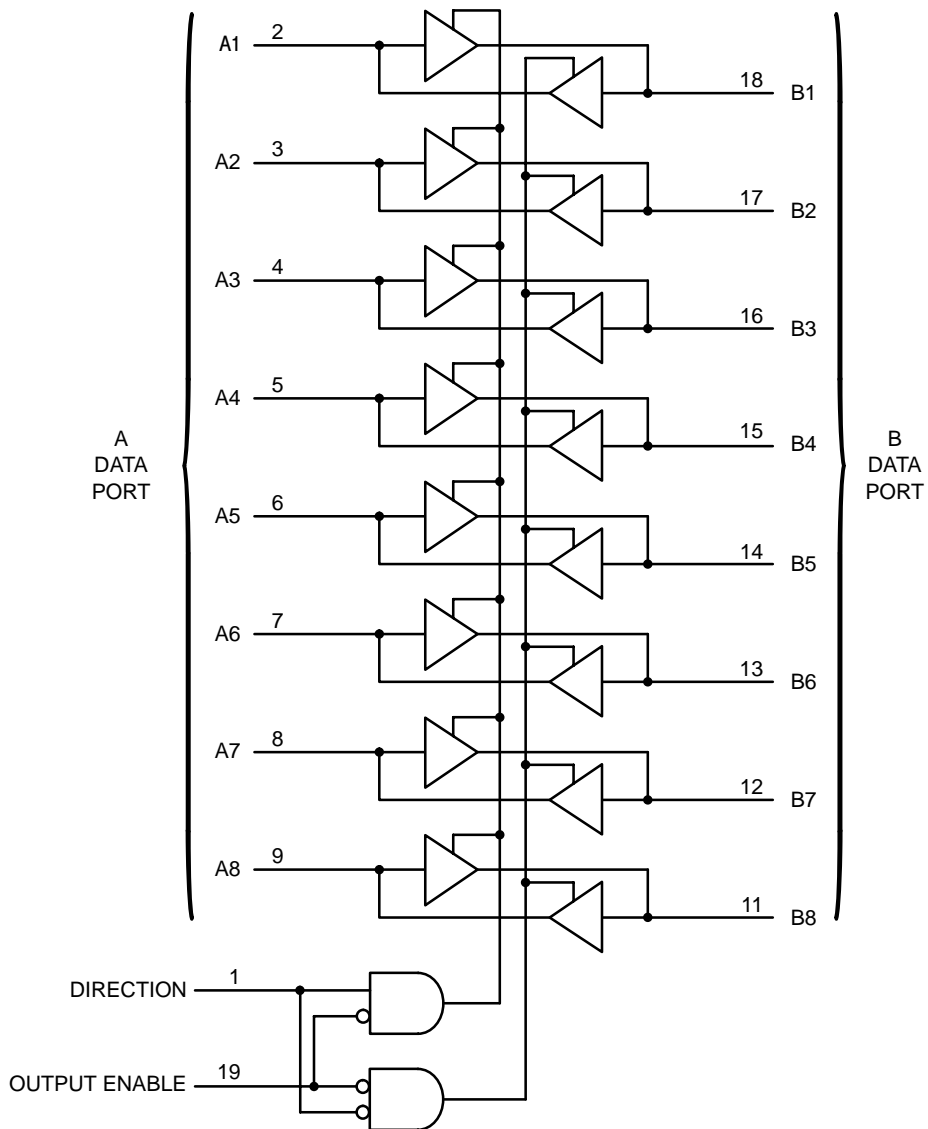
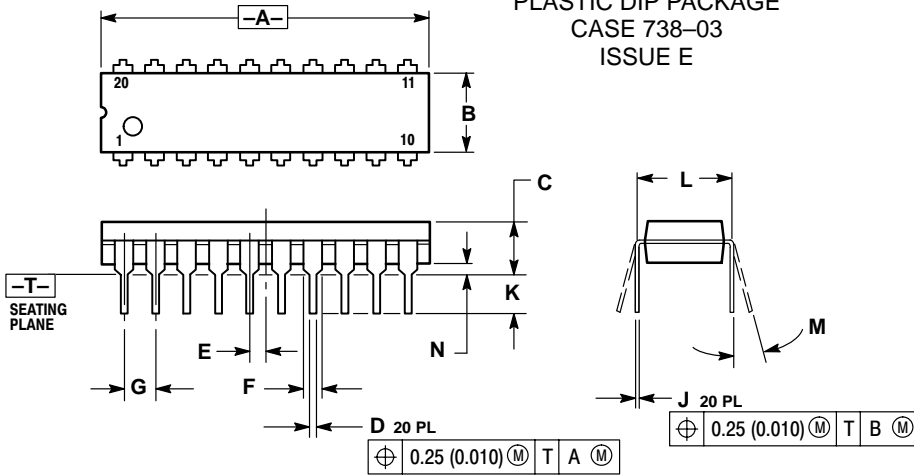


Figure 7. Expanded Logic Diagram

MC74HC245A

PACKAGE DIMENSIONS

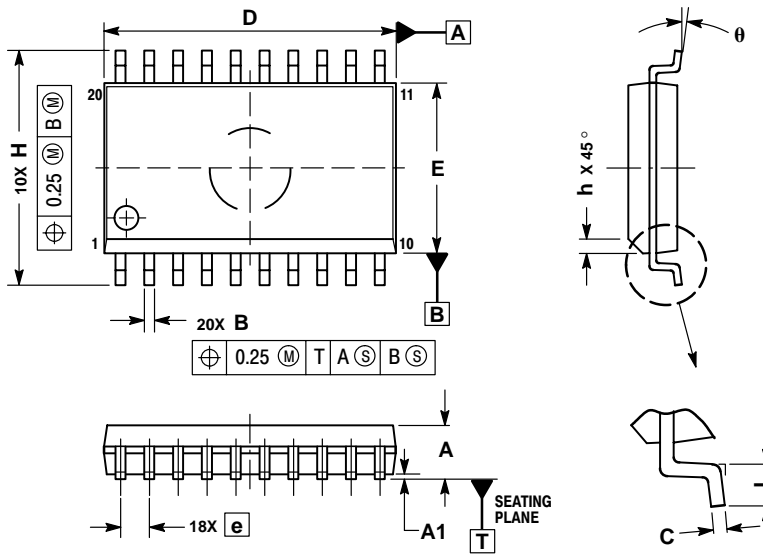
PDIP-20 N SUFFIX PLASTIC DIP PACKAGE CASE 738-03 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.010 | 1.070 | 25.66 | 27.17 |
| B | 0.240 | 0.260 | 6.10 | 6.60 |
| C | 0.150 | 0.180 | 3.81 | 4.57 |
| D | 0.015 | 0.022 | 0.39 | 0.55 |
| E | 0.050 BSC | | 1.27 BSC | |
| F | 0.050 | 0.070 | 1.27 | 1.77 |
| G | 0.100 BSC | | 2.54 BSC | |
| J | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.110 | 0.140 | 2.80 | 3.55 |
| L | 0.300 BSC | | 7.62 BSC | |
| M | 0° | 15° | 0° | 15° |
| N | 0.020 | 0.040 | 0.51 | 1.01 |

SO-20 DW SUFFIX CASE 751D-05 ISSUE F



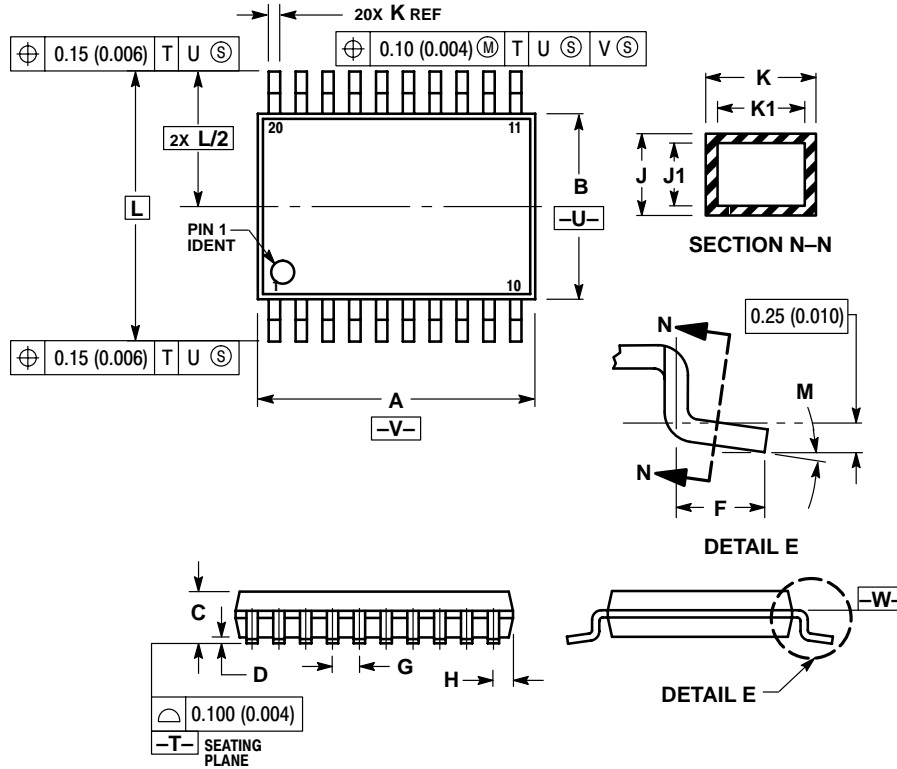
- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | |
|----------|-------------|-------|
| | MIN | MAX |
| A | 2.35 | 2.65 |
| A1 | 0.10 | 0.25 |
| B | 0.35 | 0.49 |
| C | 0.23 | 0.32 |
| D | 12.65 | 12.95 |
| E | 7.40 | 7.60 |
| e | 1.27 BSC | |
| H | 10.05 | 10.55 |
| h | 0.25 | 0.75 |
| L | 0.50 | 0.90 |
| θ | 0° | 7° |

MC74HC245A

PACKAGE DIMENSIONS

TSSOP-20
DT SUFFIX
20 PIN PLASTIC TSSOP PACKAGE
CASE 948E-02
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 6.40 | 6.60 | 0.252 | 0.260 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.27 | 0.37 | 0.011 | 0.015 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center
4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-0031
Phone: 81-3-5740-2700
Email: r14525@onsemi.com

ON Semiconductor Website: <http://onsemi.com>

For additional information, please contact your local Sales Representative.